# LNJ814W83RA

### Hight Bright Surface Mounting Chip LED

**USS Type** 

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol Rating		Unit	
Power dissipation	$P_{D}$	40	mW	
Forward current	$I_{\mathrm{F}}$	15	mA	
Pulse forward current *	I <sub>FP</sub> 40		mA	
Reverse voltage	V <sub>R</sub>	4	V	
Operating ambient temperature	T <sub>opr</sub>	-30 to +85	°C	
Storage temperature	T <sub>stg</sub>	-40 to +100	°C	

Note) \*: The condition of I<sub>FP</sub> is duty 10%, pulse width 10 ms.

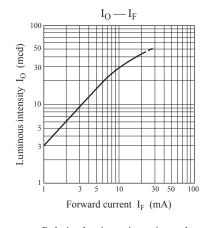
#### ■ Lighting Color

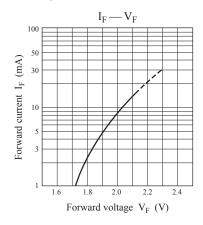
• Orange

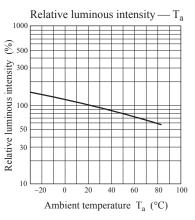
#### ■ Electro-Optical Characteristics $T_a = 25$ °C±3°C

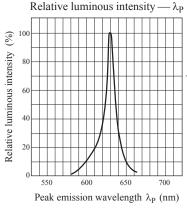
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	I <sub>O</sub>	$I_F = 5 \text{ mA}$	7.0	15.0		mcd
Reverse current	$I_R$	$V_R = 4 V$			100	μΑ
Forward voltage	V <sub>F</sub>	$I_F = 5 \text{ mA}$		1.9	2.5	V
Peak emission wavelength	$\lambda_{\mathrm{P}}$	$I_F = 5 \text{ mA}$		630		nm
Dominant emission wavelength	$\lambda_{\mathrm{d}}$	$I_F = 5 \text{ mA}$		620		nm
Spectral half band width	Δλ	$I_F = 5 \text{ mA}$		15.0		nm

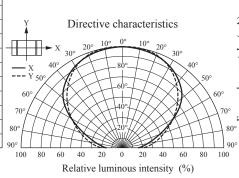
Note) Be careful of the product destruction by static electricity.

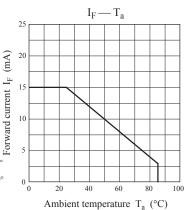






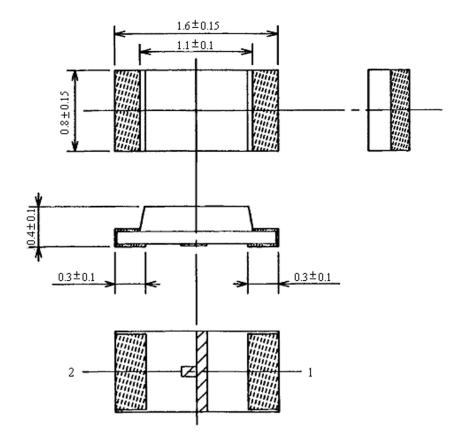






#### ■ Package (Unit: mm)

## KLTFTN2K1400



- Pin name
  - 1: Anode
  - 2: Cathode

2 SHD00620BEK

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